

ABSTRACT OF THE DISCLOSURE

A method and apparatus for manufacturing or assembling a plurality of printed circuit boards to reduce rework at a printed circuit board assembly facility, which may include the following: cutting a first solder paste stencil based on a first solder paste stencil data set on a solder paste stencil cutting machine or device; utilizing the first stencil to apply solder paste to a first printed circuit board at a manufacturing or assembly facility; identifying a solder paste error condition with solder paste error information on the first printed circuit board; transmitting the solder paste error information for remote analysis; generating an adjusted first data set; transmitting the adjusted first data set to the printed circuit board manufacturing or assembly facility; utilizing the adjusted first data set to cut another solder paste stencil based on the adjusted stencil data; and utilizing the adjusted first solder paste stencil to manufacture a second printed circuit board without the solder paste error condition.